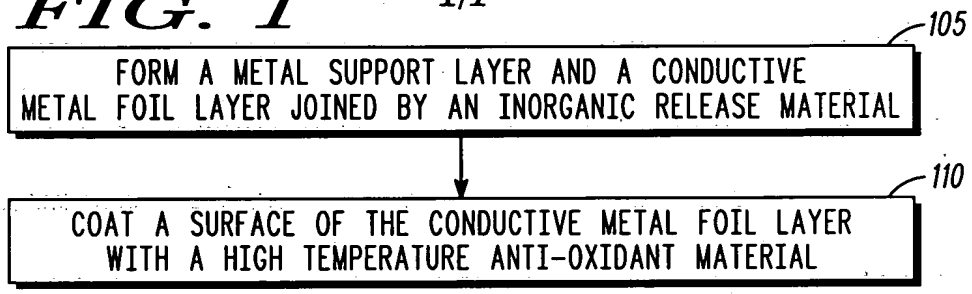
FIG. 1


105
FORM A METAL SUPPORT LAYER AND A CONDUCTIVE METAL FOIL LAYER JOINED BY AN INORGANIC RELEASE MATERIAL
110
COAT A SURFACE OF THE CONDUCTIVE METAL FOIL LAYER WITH A HIGH TEMPERATURE ANTI-OXIDANT MATERIAL

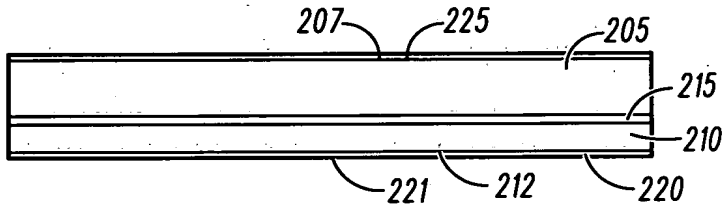
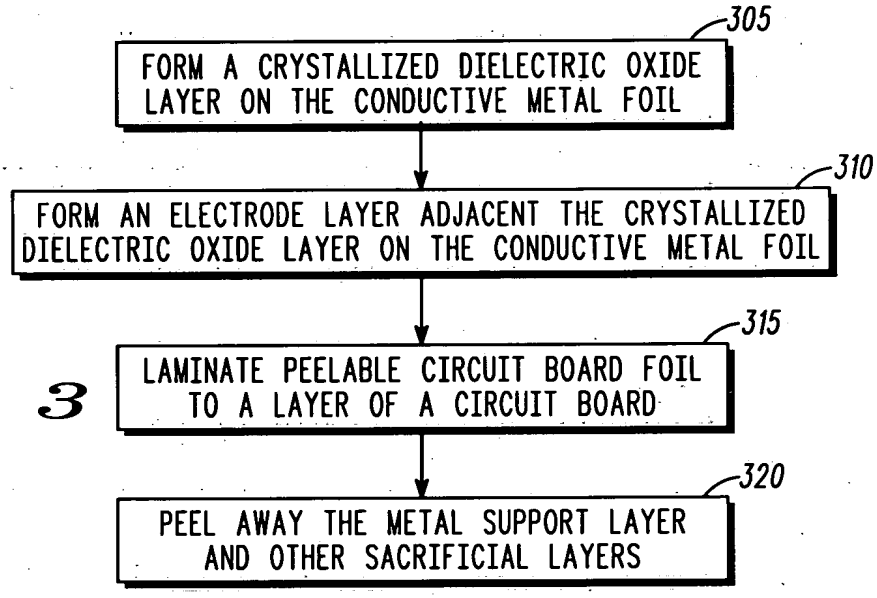


FIG. 2

FIG. 3


305
FORM A CRYSTALLIZED DIELECTRIC OXIDE LAYER ON THE CONDUCTIVE METAL FOIL
310
FORM AN ELECTRODE LAYER ADJACENT THE CRYSTALLIZED DIELECTRIC OXIDE LAYER ON THE CONDUCTIVE METAL FOIL
315
LAMINATE PEELABLE CIRCUIT BOARD FOIL TO A LAYER OF A CIRCUIT BOARD
320
PEEL AWAY THE METAL SUPPORT LAYER AND OTHER SACRIFICIAL LAYERS

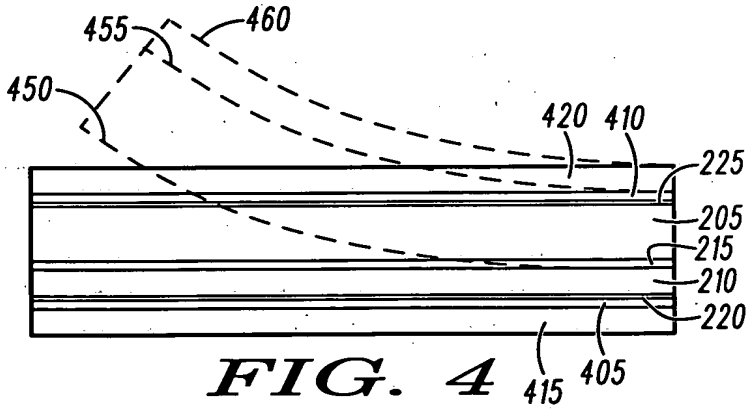


FIG. 4